Insulated Metallic Substrate PCB

PCB Type:	Singlesided
Min. drill endsize:	1.0 mm
Min. tracksize:	0.125 mm
Min. airgap	0.125 mm
Soldermask:	Green / White / Black
Silkscreen:	White / Black
Surface:	HAL leadfree
Gap contour - copper:	0.3 mm
Contour processing:	Routing
Copper thickness:	0.035 mm
Dielectric substrate:	0.100 mm
Carrier material / Aluminium:	1.5 mm

Optional: It is possible to have depth milling, drills with threads (extra charge applies). This data must be supplied in a separate DXF or Target Frontpanel Designer file.